



Title of Change:	Change AR1335/AR0144 CSP minimal packaging size from 1000 to 300.	
Effective date:	29 June 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or <anna.chou@onsemi.com>	
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.	
Change Category:	<input type="checkbox"/> Wafer Fab <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>minimal packaging size</u>	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: KYEC
Description and Purpose:	To change AR1335/AR0144 CSP minimal packaging size from 1000 to 300 since marketing request.	
List of Affected Parts:	AR1335CSSC11SMKA0-CP1 AR1335CSSC11SMKA0-CR1 AR0144CSSM20SUKA0-CPBR1 AR0144CSSM20SUKA0-CRBR1	



Appendix A: Changed Products

Product	Customer Part Number
AR0144CSSM20SUKA0-CPBR1	
AR0144CSSM20SUKA0-CRBR1	
AR1335CSC11SMKA0-CP1	
AR1335CSC11SMKA0-CR1	